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June 29, 2026

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Representative: Susumu Saito, Representative Director & Chief
Executive Officer
(Securities code: 9509; TSE Prime Market, Sapporo Securities Exchange)
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Notice Regarding Issuance of Publicly Offered Hybrid Corporate Bonds (Subordinated Corporate Bonds)

Hokkaido Electric Power Company, Inc. (the “Company”) announces that today it has decided to issue, through a public offering, its first series of unsecured subordinated corporate bonds with interest deferral option and early redemption option (the “Publicly Offered Hybrid Corporate Bonds”).

1. Purpose and Background of the Issuance of the Publicly Offered Hybrid Corporate Bonds

The Company raised 80 billion yen through a hybrid loan in August 2019 as a new financing method that would contribute to strengthening its financial position. As the first optional prepayment date of the hybrid loan is scheduled for August 31, 2026, the Company, with the aim of maintaining the stability of its financial base, has decided to prepay the hybrid loan in full and issue the Publicly Offered Hybrid Corporate Bonds to procure funds for that prepayment.

2. Features of the Publicly Offered Hybrid Corporate Bonds

The Publicly Offered Hybrid Corporate Bonds have characteristics intermediate between equity and debt. While share dilution will not occur because they are debt instruments, they have characteristics and features similar to those of equity, such as an option to defer interest payments, a long-dated maturity profile, and subordination in liquidation and bankruptcy proceedings. Therefore, the Company expects that 50% of the issue amount will be recognized as equity by Rating and Investment Information, Inc. and Japan Credit Rating Agency, Ltd.

3. Schedule

The Company has mandated SMBC Nikko Securities Inc., Mizuho Securities Co., Ltd., Mitsubishi UFJ Morgan Stanley Securities Co., Ltd., and Daiwa Securities Co. Ltd. as joint lead managers. The Company will determine the terms and conditions of the issuance after comprehensively considering market demand, interest rate trends, and other factors, and will announce them promptly after such determination.

Note: This announcement is for the purpose of public disclosure regarding the issuance of the Company’s publicly offered hybrid corporate bonds (subordinated corporate bonds), and not for the purpose of any solicitation for investment or any act related thereto.

Outline of the Publicly Offered Hybrid Corporate Bonds (Planned)

Name	Hokkaido Electric Power Company, Inc. First series of unsecured subordinated corporate bonds with interest deferral option and early redemption option
Total amount of the issue	80 billion yen
Pricing date	Late July 2026
Settlement date	The 4th business day following the pricing date
Maturity date	To be determined (after 37 years)
Early redemption	To be determined; provided, however, that optional redemption of all (but not part) of the Hybrid Bonds is possible on the first optional redemption date (to be determined; after 7 years) and on each interest payment date thereafter.
Lead managers	SMBC Nikko Securities Inc., Mizuho Securities Co., Ltd., Mitsubishi UFJ Morgan Stanley Securities Co., Ltd., and Daiwa Securities Co. Ltd.

(Reference) Outline of the Hybrid Loan to be Prepaid

Total amount raised	80 billion yen
Prepayment date	August 31, 2026 (the first optional prepayment date) (planned)
Total prepayment amount	80 billion yen

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